PCN Number: 20220804001.1 PCN Date: August 04, 2022											
Customer Contact: PCN Manager Nov 08, 2022 Sample requests accepted until: Sept 08, 2022* Sample requests received after (Sept 08, 2022) will not be supported. Sept 08, 2022* Sample requests received after (Sept 08, 2022) will not be supported. Sept 08, 2022* Sample requests received after (Sept 08, 2022) will not be supported. Sept 08, 2022* Sample requests accepted until: Sept 08, 2022* Sept 08, 2022* Sample requests accepted until: Sept 08, 2022* Sept 08, 2022* Sample requests accepted until: Sept 08, 2022* Sept 08, 2	PCN Number:		2022080	20220804001.1				PCI	N Date:		t 04,
Nov 08, 2022 Sample requests accepted until: Sept 08, 2022 Sample requests received after (Sept 08, 2022) will not be supported.	Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)									
*Sample requests received after (Sept 08, 2022) will not be supported. Change Type: Assembly Site Assembly Process Data Sheet Wafer Bump Site Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Bump Process Wafer Bump Process Mechanical Specification Packing/Shipping/Labeling Per Packing/Shipping/Labeling Per N Details Per N Details Description of Change: Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows: Material Current Proposed Wire type 0.96 mill Au 1.00 mil Cu Reason for Change: Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None. Impact on Environmental Ratings Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. RoHS REACH Green Status IEC 62474 No Change Changes to product identification resulting from this PCN: None. Product Affected:	Customer Contact: PCN Manager Dept: Quality Services										
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Qualification Report

Approve Date 14-JULY -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Conditio n	Durati on	Qual Device: <u>OPA1679IR</u> <u>UMR</u>	QBS Package/Pro duct Reference : OPA1679QRU MRQ1	QBS Package Reference : BQ24193R GER	QBS Package Reference: BQ25890HR TWR	QBS Package Reference : BQ9003R SMR	QBS Package Reference: <u>TMP451AI</u> <u>DQFR</u>
HAS T	A2	Biased HAST	130C/85 %RH	96 Hours	-	3/231/0	-	-	-	-
UHA ST	А3	Autodave	121C/15 psig	96 Hours	-	-	3/231/0	3/231/0	3/231/0	3/231/0
UHA ST	А3	Unbiased HAST	130C/85 %RH	96 Hours	-	3/231/0	-	-	-	-
TC	A4	Temperatur e Cyde	- 65C/150 C	500 Cycles	-	3/231/0-	3/231/0	3/231/0	3/231/0	3/231/0
HTS L	A6	High Temperature Storage Life	175C	500 Hours	-	1/45/0	-	-	-	-
HT OL	B1	Life Test	135C Ta/150C Tj	408 Hours	-	3/231/0	-	-	-	-
PD	C 4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	-	-
CHA R	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	-	-
MQ	10. O	Manufactura bility	-	-	3/0					

QBS: Qual By Similarity

Qual Device OPA1679IRUMR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail					
WW PCN Team	PCN www admin team@list.ti.com					

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